

General Description

- Trench Power MV MOSFET technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Optimized for fast-switching applications

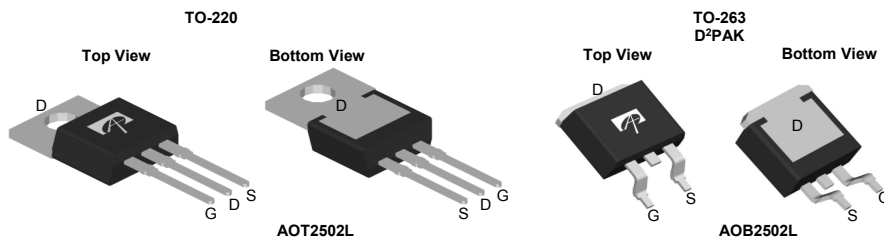
Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Industrial and Motor Drive applications

Product Summary

| | |
|---------------------------------|------------------------------------|
| V_{DS} | 150V |
| I_D (at $V_{GS}=10V$) | 106A |
| $R_{DS(ON)}$ (at $V_{GS}=10V$) | < 11m Ω (10.7m Ω^*) |

100% UIS Tested
 100% Rg Tested



| Orderable Part Number | Package Type | Form | Minimum Order Quantity |
|-----------------------|--------------|-------------|------------------------|
| AOT2502L | TO-220 | Tube | 1000 |
| AOB2502L | TO-263 | Tape & Reel | 800 |

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Maximum | Units |
|--|----------------|-------------------------|------------------|
| Drain-Source Voltage | V_{DS} | 150 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current | I_D | $T_C=25^\circ\text{C}$ | 106 |
| | | $T_C=100^\circ\text{C}$ | 67 |
| Pulsed Drain Current ^C | I_{DM} | 250 | A |
| Continuous Drain Current | I_{DSM} | $T_A=25^\circ\text{C}$ | 18.5 |
| | | $T_A=70^\circ\text{C}$ | 14.5 |
| Avalanche Current ^C | I_{AS} | 40 | A |
| Avalanche energy $L=0.3\text{mH}$ ^C | E_{AS} | 240 | mJ |
| V_{DS} Spike | V_{SPIKE} | 180 | V |
| Power Dissipation ^B | P_D | $T_C=25^\circ\text{C}$ | 277 |
| | | $T_C=100^\circ\text{C}$ | 111 |
| Power Dissipation ^A | P_{DSM} | $T_A=25^\circ\text{C}$ | 8.3 |
| | | $T_A=70^\circ\text{C}$ | 5.3 |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | $^\circ\text{C}$ |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Units |
|--|-----------------|--------------|------|--------------------|
| Maximum Junction-to-Ambient ^A | $R_{\theta JA}$ | 12 | 15 | $^\circ\text{C/W}$ |
| Maximum Junction-to-Ambient ^{A,D} | | Steady-State | 50 | 60 |
| Maximum Junction-to-Case | $R_{\theta JC}$ | 0.35 | 0.45 | $^\circ\text{C/W}$ |

* Surface mount package TO-263

Electrical Characteristics (T_J=25°C unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units | |
|-----------------------------|---------------------------------------|--|-----|-------------|------------|-------|----|
| STATIC PARAMETERS | | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | I _D =250μA, V _{GS} =0V | 150 | | | V | |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =150V, V _{GS} =0V T _J =55°C | | | 1 5 | μA | |
| I _{GSS} | Gate-Body leakage current | V _{DS} =0V, V _{GS} =±20V | | | ±100 | nA | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 3.5 | 4.3 | 5.1 | V | |
| R _{DS(on)} | Static Drain-Source On-Resistance | V _{GS} =10V, I _D =20A TO-220 T _J =125°C | | 9.2 17.8 | 11 21.5 | mΩ | |
| | | V _{GS} =10V, I _D =20A TO-263 | | 8.9 | 10.7 | mΩ | |
| g _{FS} | Forward Transconductance | V _{DS} =5V, I _D =20A | | 50 | | S | |
| V _{SD} | Diode Forward Voltage | I _S =1A, V _{GS} =0V | | 0.7 | 1 | V | |
| I _S | Maximum Body-Diode Continuous Current | | | | 106 | A | |
| DYNAMIC PARAMETERS | | | | | | | |
| C _{iss} | Input Capacitance | V _{GS} =0V, V _{DS} =75V, f=1MHz | | 3010 | | pF | |
| C _{oss} | Output Capacitance | | | | 345 | | pF |
| C _{riss} | Reverse Transfer Capacitance | | | | 14 | | pF |
| R _g | Gate resistance | f=1MHz | 1 | 2 | 3 | Ω | |
| SWITCHING PARAMETERS | | | | | | | |
| Q _{g(10V)} | Total Gate Charge | V _{GS} =10V, V _{DS} =75V, I _D =20A | | 43 | 60 | nC | |
| Q _{gs} | Gate Source Charge | | | | 18 | | nC |
| Q _{gd} | Gate Drain Charge | | | | 10 | | nC |
| t _{D(on)} | Turn-On DelayTime | V _{GS} =10V, V _{DS} =75V, R _L =3.75Ω, R _{GEN} =3Ω | | 19 | | ns | |
| t _r | Turn-On Rise Time | | | | 24 | | ns |
| t _{D(off)} | Turn-Off DelayTime | | | | 30 | | ns |
| t _f | Turn-Off Fall Time | | | | 8.5 | | ns |
| t _{rr} | Body Diode Reverse Recovery Time | I _F =20A, dI/dt=500A/μs | | 75 | | ns | |
| Q _{rr} | Body Diode Reverse Recovery Charge | I _F =20A, dI/dt=500A/μs | | 880 | | nC | |

A. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on R_{θJA} ≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 150° C may be used if the PCB allows it.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature T_{J(MAX)}=150° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

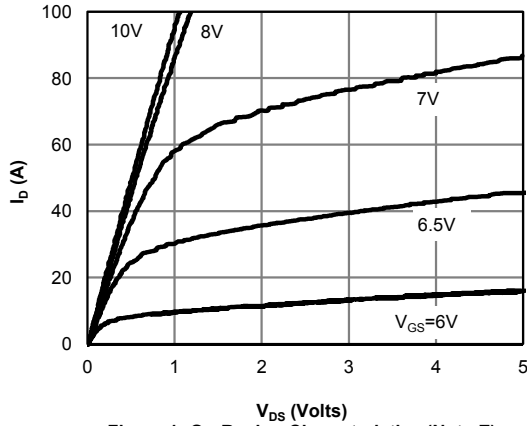


Figure 1: On-Region Characteristics (Note E)

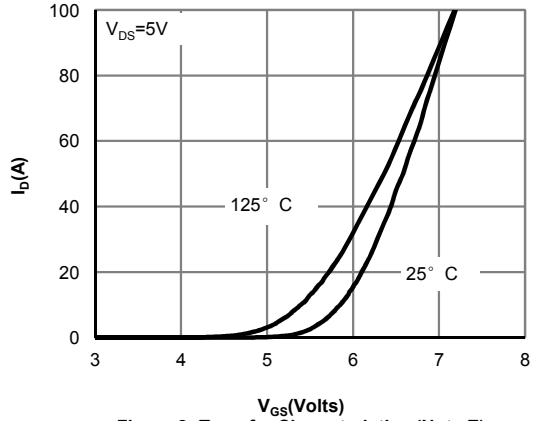


Figure 2: Transfer Characteristics (Note E)

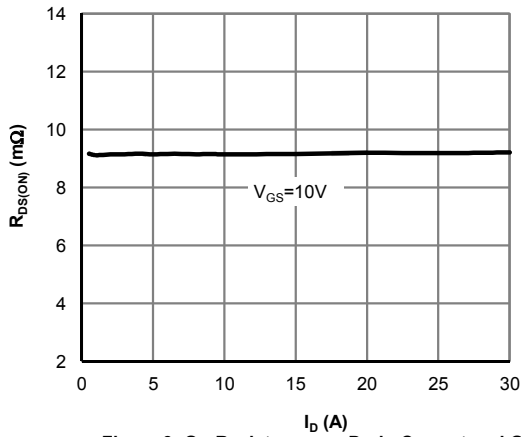


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

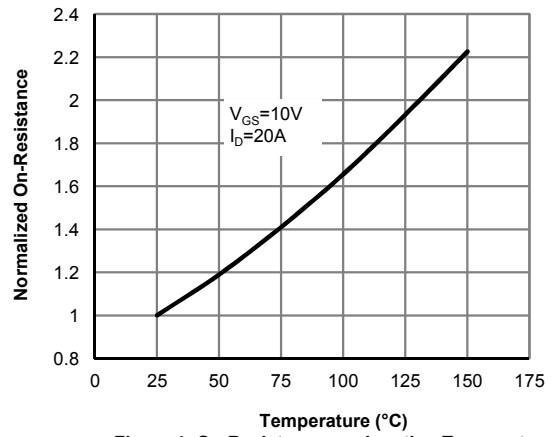


Figure 4: On-Resistance vs. Junction Temperature (Note E)

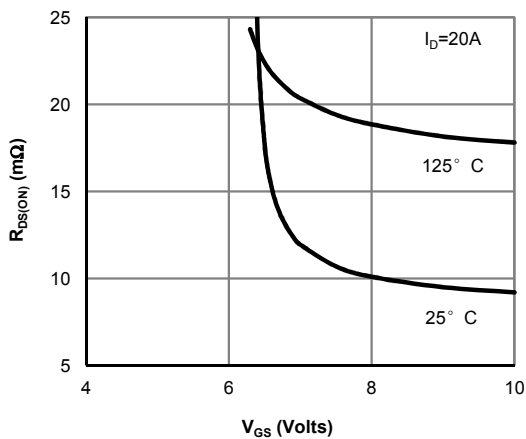


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

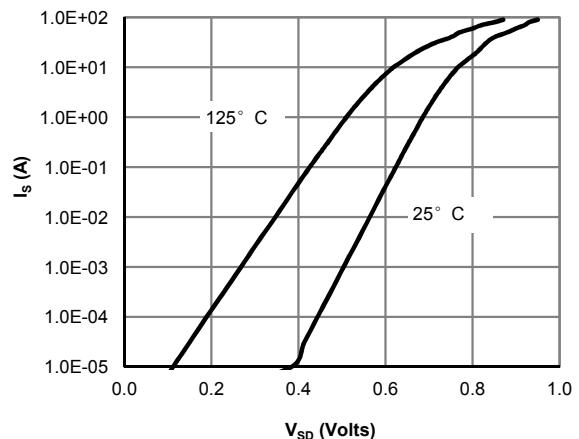


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

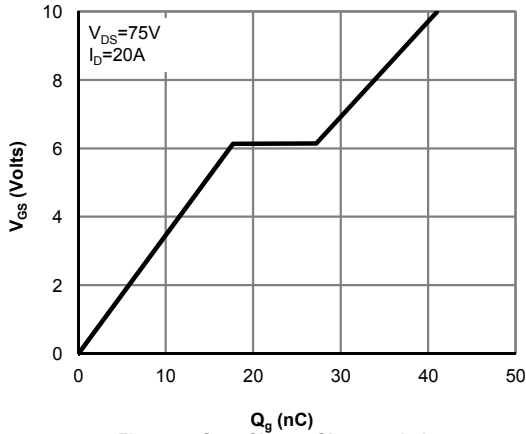


Figure 7: Gate-Charge Characteristics

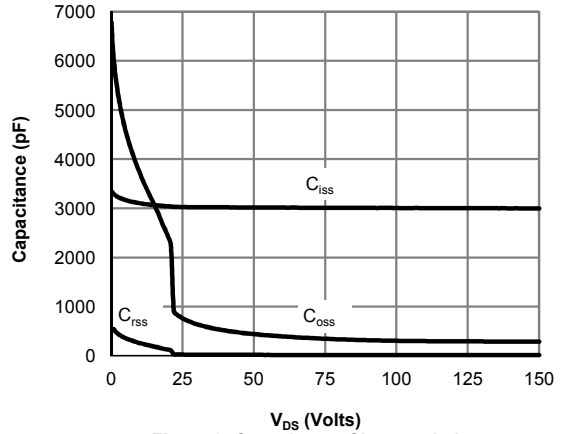


Figure 8: Capacitance Characteristics

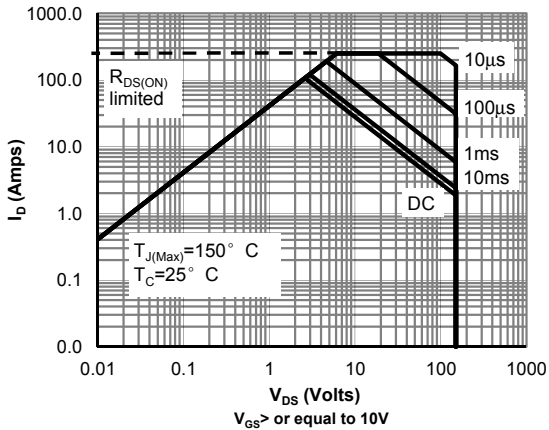


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

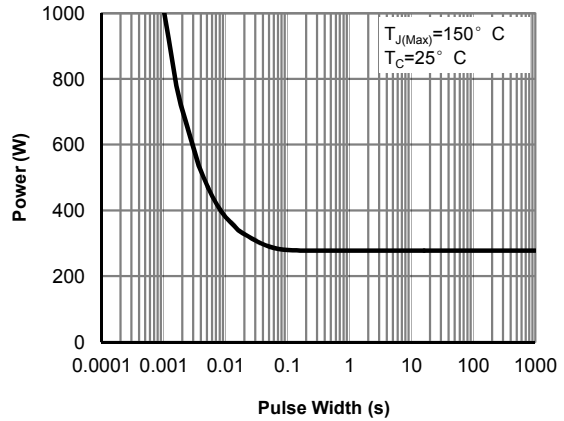


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

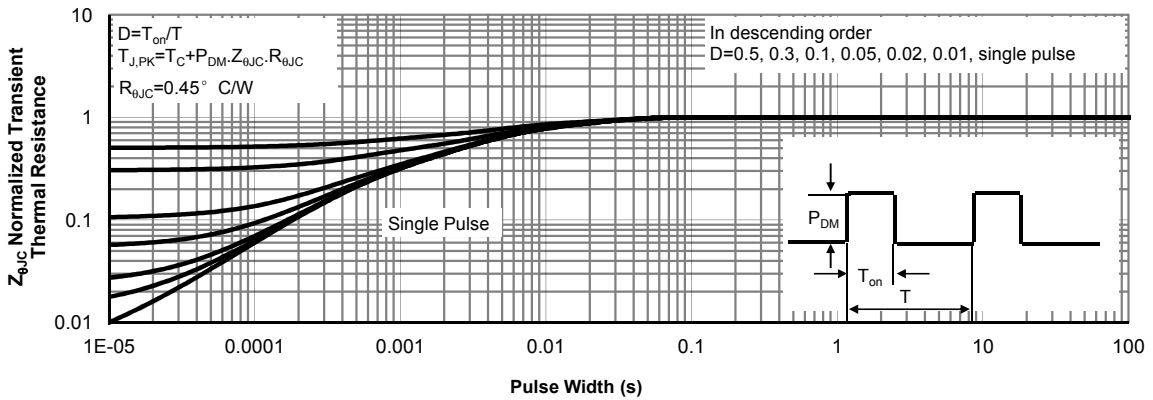


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

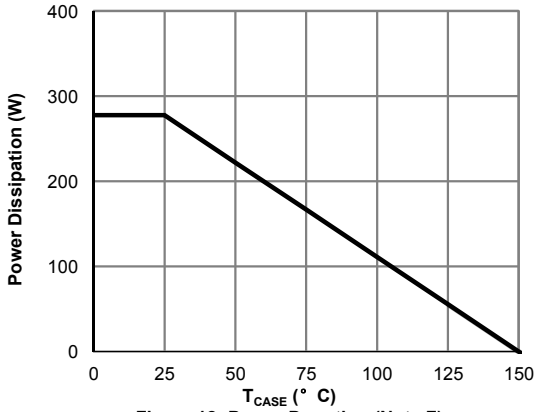


Figure 12: Power De-rating (Note F)

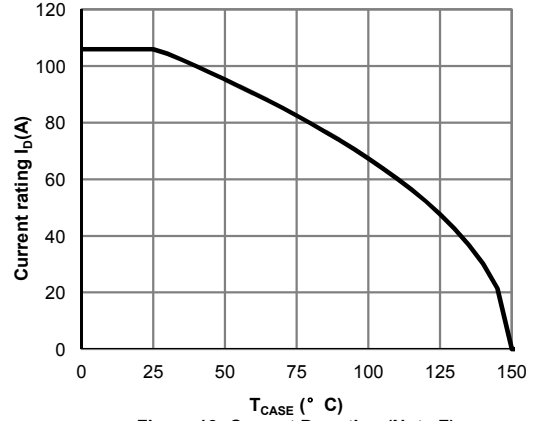


Figure 13: Current De-rating (Note F)

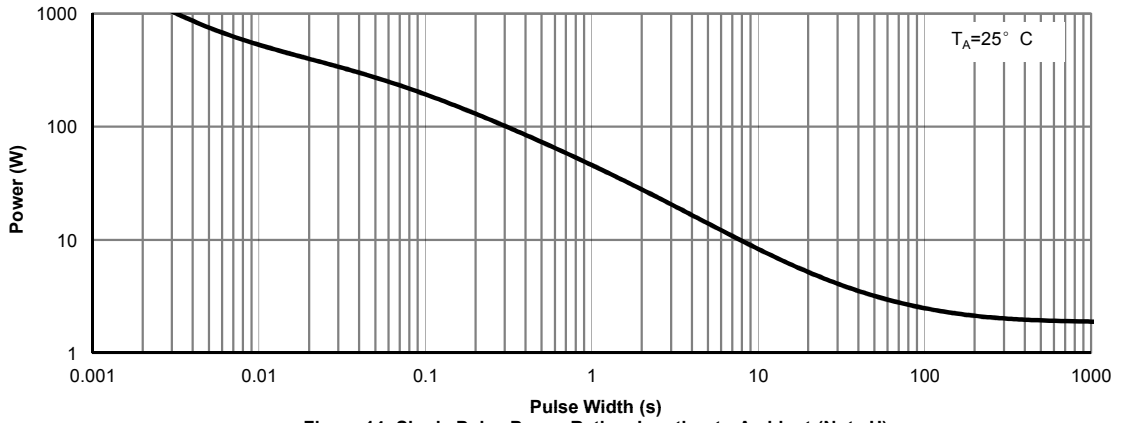


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

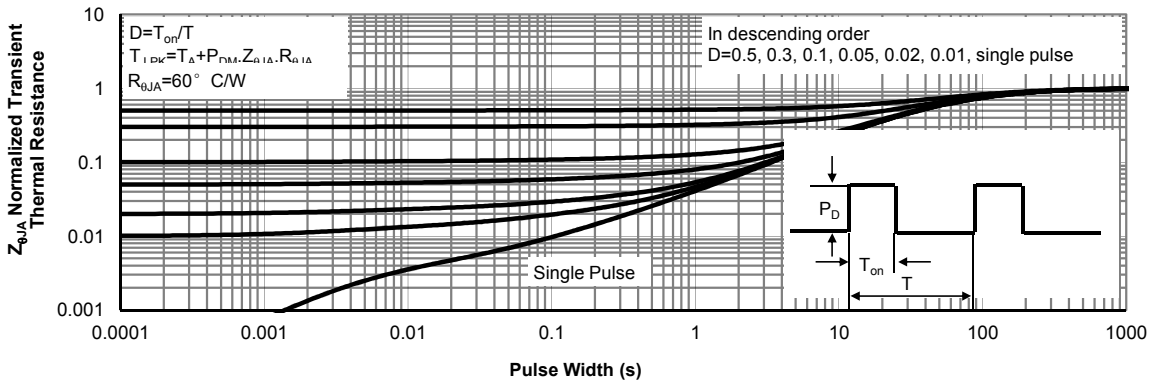
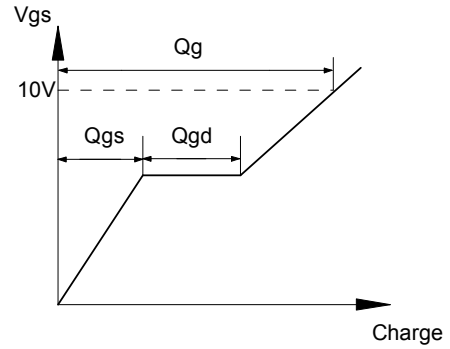
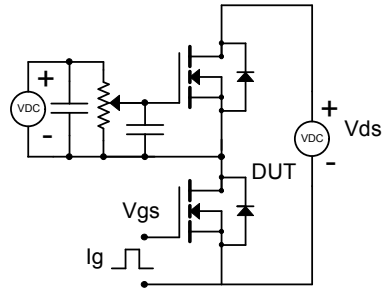
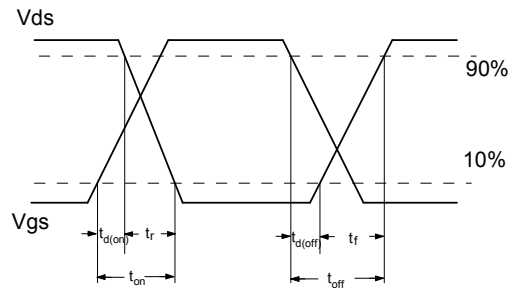
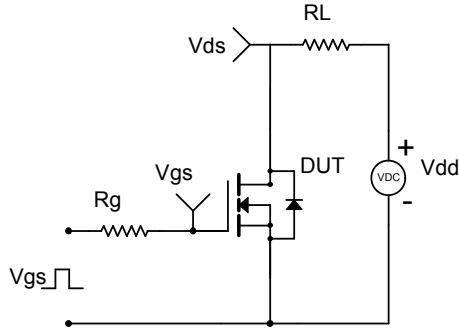


Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

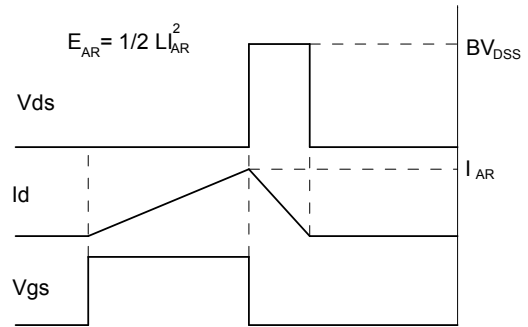
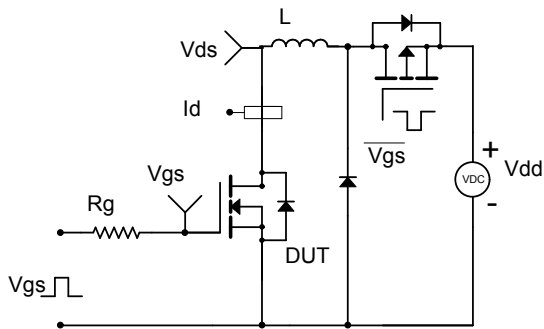
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

